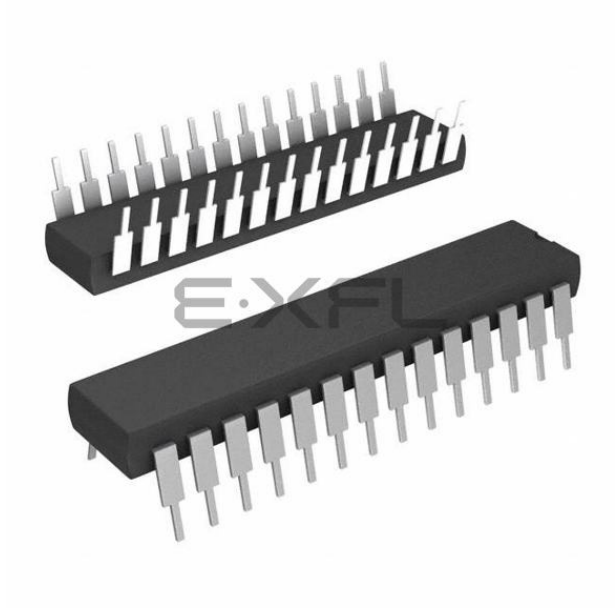

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	24
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 11x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f882-e-sp

TABLE 1-2: PIC16F884/887 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RD7/P1D	RD7	TTL	CMOS	General purpose I/O.
	P1D	AN	—	PWM output.
RE0/AN5	RE0	TTL	CMOS	General purpose I/O.
	AN5	AN	—	A/D Channel 5.
RE1/AN6	RE1	TTL	CMOS	General purpose I/O.
	AN6	AN	—	A/D Channel 6.
RE2/AN7	RE2	TTL	CMOS	General purpose I/O.
	AN7	AN	—	A/D Channel 7.
RE3/$\overline{\text{MCLR}}$/V_{PP}	RE3	TTL	—	General purpose input.
	$\overline{\text{MCLR}}$	ST	—	Master Clear with internal pull-up.
	V_{PP}	HV	—	Programming voltage.
V_{SS}	V_{SS}	Power	—	Ground reference.
V_{DD}	V_{DD}	Power	—	Positive supply.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open-Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels
HV = High Voltage XTAL = Crystal

3.2.3.8 RA7/OSC1/CLKIN

Figure 3-8 shows the diagram for this pin. This pin is configurable to function as one of the following:

- a general purpose I/O
- a crystal/resonator connection
- a clock input

FIGURE 3-8: BLOCK DIAGRAM OF RA7

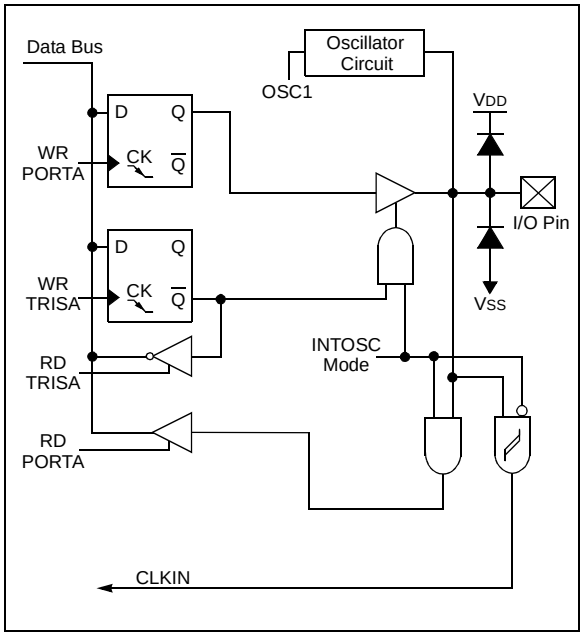


TABLE 3-1: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ADCON0	ADCS1	ADCS0	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON	104
ANSEL	ANS7	ANS6	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0	41
CM1CON0	C1ON	C1OUT	C1OE	C1POL	—	C1R	C1CH1	C1CH0	89
CM2CON0	C2ON	C2OUT	C2OE	C2POL	—	C2R	C2CH1	C2CH0	90
CM2CON1	MC1OUT	MC2OUT	C1RSEL	C2RSEL	—	—	T1GSS	C2SYNC	92
PCON	—	—	ULPWUE	SBOREN	—	—	$\overline{\text{POR}}$	$\overline{\text{BOR}}$	37
OPTION_REG	$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	31
PORTA	RA7	RA6	RA5	RA4	RA3	RA2	RA1	RA0	40
SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	177
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	40

Legend: x = unknown, u = unchanged, – = unimplemented locations read as '0'. Shaded cells are not used by PORTA.

3.3 PORTB and TRISB Registers

PORTB is an 8-bit wide, bidirectional port. The corresponding data direction register is TRISB (Register 3-6). Setting a TRISB bit (= 1) will make the corresponding PORTB pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISB bit (= 0) will make the corresponding PORTB pin an output (i.e., enable the output driver and put the contents of the output latch on the selected pin). Example 3-3 shows how to initialize PORTB.

Reading the PORTB register (Register 3-5) reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified and then written to the PORT data latch.

The TRISB register (Register 3-6) controls the PORTB pin output drivers, even when they are being used as analog inputs. The user should ensure the bits in the TRISB register are maintained set when using them as analog inputs. I/O pins configured as analog input always read '0'. Example 3-3 shows how to initialize PORTB.

EXAMPLE 3-3: INITIALIZING PORTB

```
BANKSEL PORTB       ;
CLRF    PORTB       ;Init PORTB
BANKSEL TRISB       ;
MOVLW   B'11110000' ;Set RB<7:4> as inputs
                    ;and RB<3:0> as outputs
MOVWF   TRISB       ;
```

Note:	The ANSELH register must be initialized to configure an analog channel as a digital input. Pins configured as analog inputs will read '0'.

3.4 Additional PORTB Pin Functions

PORTB pins RB<7:0> on the device family device have an interrupt-on-change option and a weak pull-up option. The following three sections describe these PORTB pin functions.

Every PORTB pin on this device family has an interrupt-on-change option and a weak pull-up option.

3.4.1 ANSELH REGISTER

The ANSELH register (Register 3-4) is used to configure the Input mode of an I/O pin to analog. Setting the appropriate ANSELH bit high will cause all digital reads on the pin to be read as '0' and allow analog functions on the pin to operate correctly.

The state of the ANSELH bits has no affect on digital output functions. A pin with TRIS clear and ANSELH set will still operate as a digital output, but the Input mode will be analog. This can cause unexpected behavior when executing read-modify-write instructions on the affected port.

3.4.2 WEAK PULL-UPS

Each of the PORTB pins has an individually configurable internal weak pull-up. Control bits WPUB<7:0> enable or disable each pull-up (see Register 3-7). Each weak pull-up is automatically turned off when the port pin is configured as an output. All pull-ups are disabled on a Power-on Reset by the $\overline{\text{RBPU}}$ bit of the OPTION register.

3.4.3 INTERRUPT-ON-CHANGE

All of the PORTB pins are individually configurable as an interrupt-on-change pin. Control bits IOCB<7:0> enable or disable the interrupt function for each pin. Refer to Register 3-8. The interrupt-on-change feature is disabled on a Power-on Reset.

For enabled interrupt-on-change pins, the present value is compared with the old value latched on the last read of PORTB to determine which bits have changed or mismatched the old value. The 'mismatch' outputs of the last read are OR'd together to set the PORTB Change Interrupt flag bit (RBIF) in the INTCON register.

This interrupt can wake the device from Sleep. The user, in the Interrupt Service Routine, clears the interrupt by:

a) Any read or write of PORTB. This will end the mismatch condition.
b) Clear the flag bit RBIF.

A mismatch condition will continue to set flag bit RBIF. Reading or writing PORTB will end the mismatch condition and allow flag bit RBIF to be cleared. The latch holding the last read value is not affected by a $\overline{\text{MCLR}}$ nor Brown-out Reset. After these Resets, the RBIF flag will continue to be set if a mismatch is present.

Note:	If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RBIF interrupt flag may not get set. Furthermore, since a read or write on a port affects all bits of that port, care must be taken when using multiple pins in Interrupt-on-Change mode. Changes on one pin may not be seen while servicing changes on another pin.

9.1 ADC Configuration

When configuring and using the ADC the following functions must be considered:

- Port configuration
- Channel selection
- ADC voltage reference selection
- ADC conversion clock source
- Interrupt control
- Results formatting

9.1.1 PORT CONFIGURATION

The ADC can be used to convert both analog and digital signals. When converting analog signals, the I/O pin should be configured for analog by setting the associated TRIS and ANSEL bits. See the corresponding Port section for more information.

Note:	Analog voltages on any pin that is defined as a digital input may cause the input buffer to conduct excess current.

9.1.2 CHANNEL SELECTION

The CHS bits of the ADCON0 register determine which channel is connected to the sample and hold circuit.

When changing channels, a delay is required before starting the next conversion. Refer to **Section 9.2 "ADC Operation"** for more information.

9.1.3 ADC VOLTAGE REFERENCE

The VCFG bits of the ADCON1 register provide independent control of the positive and negative voltage references. The positive voltage reference can be either VDD or an external voltage source. Likewise, the negative voltage reference can be either VSS or an external voltage source.

9.1.4 CONVERSION CLOCK

The source of the conversion clock is software selectable via the ADCS bits of the ADCON0 register. There are four possible clock options:

- FOSC/2
- FOSC/8
- FOSC/32
- FRC (dedicated internal oscillator)

The time to complete one bit conversion is defined as TAD. One full 10-bit conversion requires 11 TAD periods as shown in Figure 9-2.

For correct conversion, the appropriate TAD specification must be met. See A/D conversion requirements in **Section 17.0 "Electrical Specifications"** for more information. Table 9-1 gives examples of appropriate ADC clock selections.

Note:	Unless using the FRC, any changes in the system clock frequency will change the ADC clock frequency, which may adversely affect the ADC result.

REGISTER 9-2: ADCON1: A/D CONTROL REGISTER 1

R/W-0	U-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
ADFM	—	VCFG1	VCFG0	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **ADFM:** A/D Conversion Result Format Select bit
1 = Right justified
0 = Left justified

bit 6 **Unimplemented:** Read as ‘0’

bit 5 **VCFG1:** Voltage Reference bit
1 = V_{REF-} pin
0 = V_{SS}

bit 4 **VCFG0:** Voltage Reference bit
1 = V_{REF+} pin
0 = V_{DD}

bit 3-0 **Unimplemented:** Read as ‘0’

REGISTER 9-3: ADRESH: ADC RESULT REGISTER HIGH (ADRESH) ADFM = 0

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
ADRES9	ADRES8	ADRES7	ADRES6	ADRES5	ADRES4	ADRES3	ADRES2
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **ADRES<9:2>**: ADC Result Register bits
Upper eight bits of 10-bit conversion result

REGISTER 9-4: ADRESL: ADC RESULT REGISTER LOW (ADRESL) ADFM = 0

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
ADRES1	ADRES0	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **ADRES<1:0>**: ADC Result Register bits
Lower two bits of 10-bit conversion result

bit 5-0 **Reserved**: Do not use.

REGISTER 9-5: ADRESH: ADC RESULT REGISTER HIGH (ADRESH) ADFM = 1

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	—	—	—	ADRES9	ADRES8
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-2 **Reserved**: Do not use.

bit 1-0 **ADRES<9:8>**: ADC Result Register bits
Upper two bits of 10-bit conversion result

REGISTER 9-6: ADRESL: ADC RESULT REGISTER LOW (ADRESL) ADFM = 1

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
ADRES7	ADRES6	ADRES5	ADRES4	ADRES3	ADRES2	ADRES1	ADRES0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **ADRES<7:0>**: ADC Result Register bits
Lower eight bits of 10-bit conversion result

TABLE 9-2: SUMMARY OF ASSOCIATED ADC REGISTERS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ADCON0	ADCS1	ADCS0	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON	104
ADCON1	ADFM	—	VCFG1	VCFG0	—	—	—	—	105
ANSEL	ANS7	ANS6	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0	41
ANSELH	—	—	ANS13	ANS12	ANS11	ANS10	ANS9	ANS8	49
ADRESH	A/D Result Register High Byte								106
ADRESL	A/D Result Register Low Byte								106
INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	32
PIE1	—	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	33
PIR1	—	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	35
PORTA	RA7	RA6	RA5	RA4	RA3	RA2	RA1	RA0	40
PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	49
PORTE	—	—	—	—	RE3	RE2	RE1	RE0	60
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	40
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	49
TRISE	—	—	—	—	TRISE3	TRISE2	TRISE1	TRISE0	60

Legend: x = unknown, u = unchanged, – = unimplemented read as '0'. Shaded cells are not used for ADC module.

11.5 PWM Mode

The PWM mode generates a Pulse-Width Modulated signal on the CCPx pin. The duty cycle, period and resolution are determined by the following registers:

- PR2
- T2CON
- CCPRxL
- CCPxCON

In Pulse-Width Modulation (PWM) mode, the CCP module produces up to a 10-bit resolution PWM output on the CCPx pin. Since the CCPx pin is multiplexed with the PORT data latch, the TRIS for that pin must be cleared to enable the CCPx pin output driver.

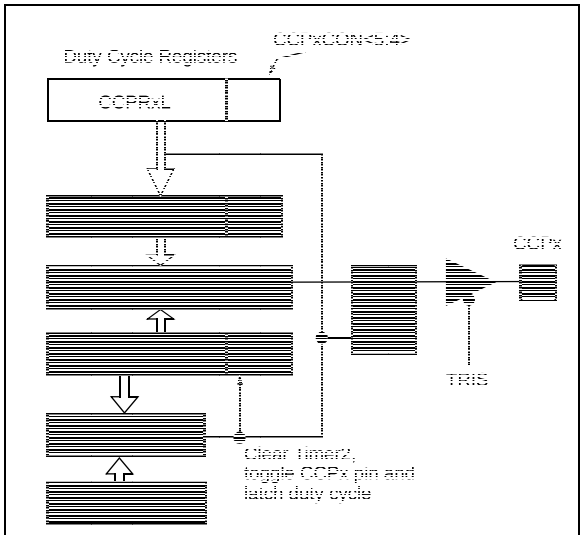
Note:	Clearing the CCPxCON register will relinquish CCPx control of the CCPx pin.

Figure 11-3 shows a simplified block diagram of PWM operation.

Figure 11-4 shows a typical waveform of the PWM signal.

For a step-by-step procedure on how to set up the CCP module for PWM operation, see **Section 11.5.7 "Setup for PWM Operation"**.

FIGURE 11-3: SIMPLIFIED PWM BLOCK DIAGRAM

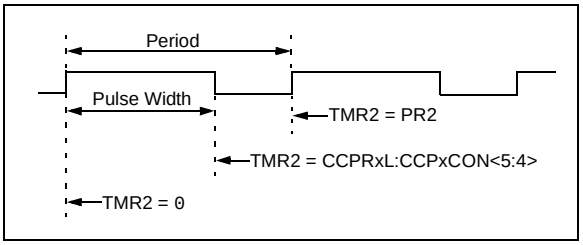


Note 1: The 8-bit timer TMR2 register is concatenated with the 2-bit internal system clock (FOSC), or 2 bits of the prescaler, to create the 10-bit time base.

2: In PWM mode, CCPRxH is a read-only register.

The PWM output (Figure 11-4) has a time base (period) and a time that the output stays high (duty cycle).

FIGURE 11-4: CCP PWM OUTPUT



11.5.1 PWM PERIOD

The PWM period is specified by the PR2 register of Timer2. The PWM period can be calculated using the formula of Equation 11-1.

EQUATION 11-1: PWM PERIOD

$$PWM\ Period = [(PR2) + 1] \bullet 4 \bullet T_{OSC} \bullet (TMR2\ Prescale\ Value)$$

Note: TOSC = 1/FOSC

When TMR2 is equal to PR2, the following three events occur on the next increment cycle:

- TMR2 is cleared
- The CCPx pin is set. (Exception: If the PWM duty cycle = 0%, the pin will not be set.)
- The PWM duty cycle is latched from CCPRxL into CCPRxH.

Note:	The Timer2 postscaler (see **Section 7.1 "Timer2 Operation"**) is not used in the determination of the PWM frequency.

12.3.1 AUTO-BAUD DETECT

The EUSART module supports automatic detection and calibration of the baud rate.

In the Auto-Baud Detect (ABD) mode, the clock to the BRG is reversed. Rather than the BRG clocking the incoming RX signal, the RX signal is timing the BRG. The Baud Rate Generator is used to time the period of a received 55h (ASCII “U”) which is the Sync character for the LIN bus. The unique feature of this character is that it has five rising edges including the Stop bit edge.

Setting the ABDEN bit of the BAUDCTL register starts the auto-baud calibration sequence (Figure 12-6). While the ABD sequence takes place, the EUSART state machine is held in Idle. On the first rising edge of the receive line, after the Start bit, the SPBRG begins counting up using the BRG counter clock as shown in Table 12-6. The fifth rising edge will occur on the RX pin at the end of the eighth bit period. At that time, an accumulated value totaling the proper BRG period is left in the SPBRGH, SPBRG register pair, the ABDEN bit is automatically cleared and the RCIF interrupt flag is set. The value in the RCREG needs to be read to clear the RCIF interrupt. RCREG content should be discarded. When calibrating for modes that do not use the SPBRGH register the user can verify that the SPBRG register did not overflow by checking for 00h in the SPBRGH register.

The BRG auto-baud clock is determined by the BRG16 and BRGH bits as shown in Table 12-6. During ABD, both the SPBRGH and SPBRG registers are used as a 16-bit counter, independent of the BRG16 bit setting. While calibrating the baud rate period, the SPBRGH and SPBRG registers are clocked at 1/8th the BRG base clock rate. The resulting byte measurement is the average bit time when clocked at full speed.

Note 1: If the WUE bit is set with the ABDEN bit, auto-baud detection will occur on the byte following the Break character (see **Section 12.3.2 “Auto-Wake-up on Break”**).

2: It is up to the user to determine that the incoming character baud rate is within the range of the selected BRG clock source. Some combinations of oscillator frequency and EUSART baud rates are not possible.

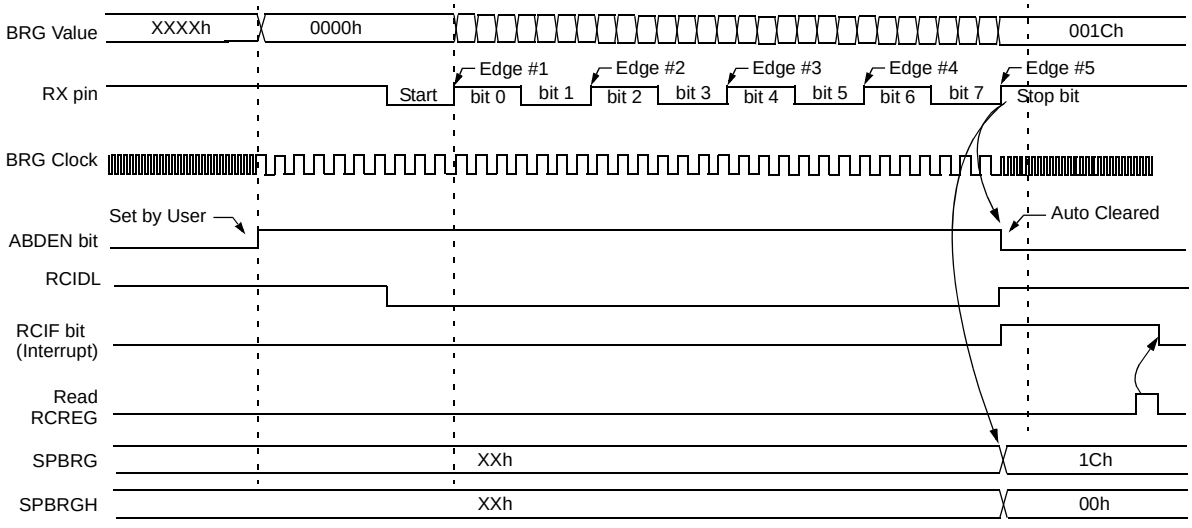
3: During the auto-baud process, the auto-baud counter starts counting at 1. Upon completion of the auto-baud sequence, to achieve maximum accuracy, subtract 1 from the SPBRGH:SPBRG register pair.

TABLE 12-6: BRG COUNTER CLOCK RATES

BRG16	BRGH	BRG Base Clock	BRG ABD Clock
0	0	FOSC/64	FOSC/512
0	1	FOSC/16	FOSC/128
1	0	FOSC/16	FOSC/128
1	1	FOSC/4	FOSC/32

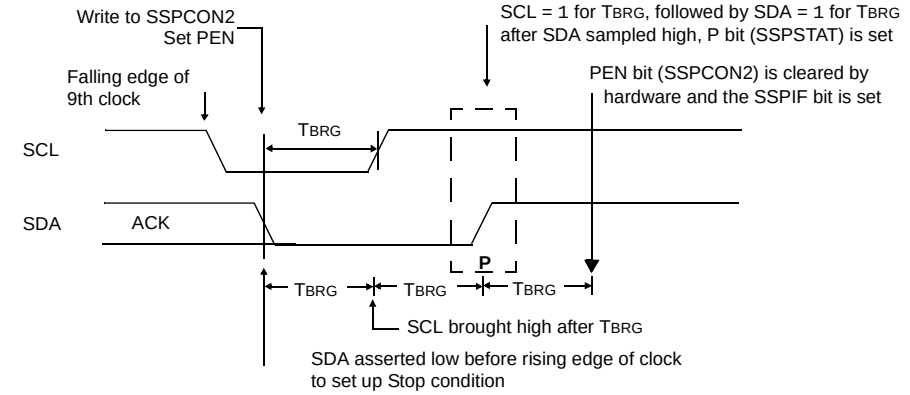
Note: During the ABD sequence, SPBRG and SPBRGH registers are both used as a 16-bit counter, independent of BRG16 setting.

FIGURE 12-6: AUTOMATIC BAUD RATE CALIBRATION



Note 1: The ABD sequence requires the **EUSART** module to be configured in Asynchronous mode

FIGURE 13-18: STOP CONDITION RECEIVE OR TRANSMIT MODE



Note: TBRG = one Baud Rate Generator period.

13.4.12 CLOCK ARBITRATION

Clock arbitration occurs when the master, during any receive, transmit or Repeated Start/Stop condition, de-asserts the SCL pin (SCL allowed to float high). When the SCL pin is allowed to float high, the Baud Rate Generator (BRG) is suspended from counting until the SCL pin is actually sampled high. When the SCL pin is sampled high, the Baud Rate Generator is reloaded with the contents of SSPADD<6:0> and begins counting. This ensures that the SCL high time will always be at least one BRG rollover count, in the event that the clock is held low by an external device (Figure 13-19).

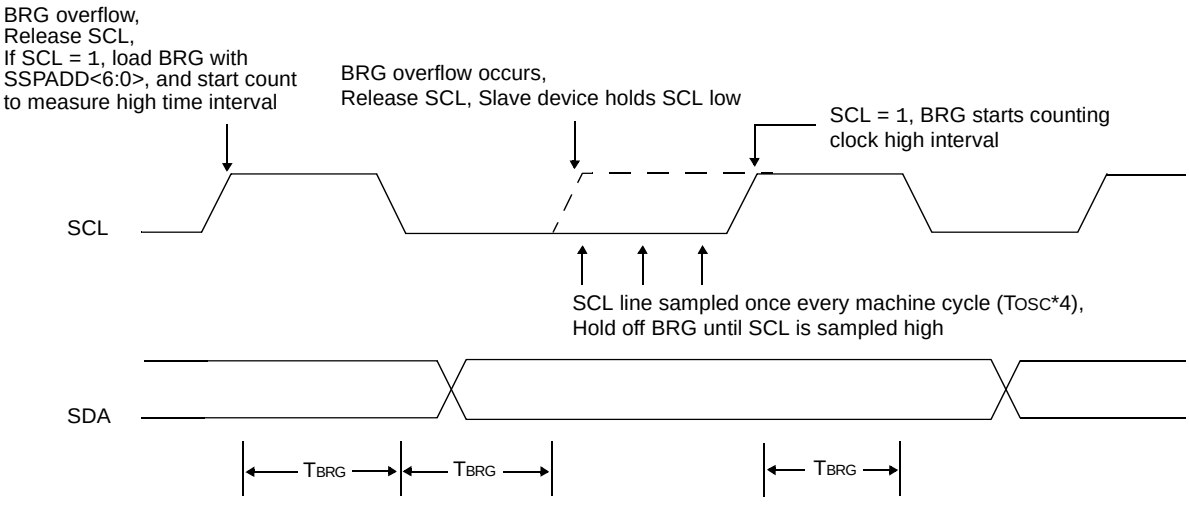
13.4.13 SLEEP OPERATION

While in Sleep mode, the I^2C module can receive addresses or data, and when an address match or complete byte transfer occurs, wake the processor from Sleep (if the MSSP interrupt is enabled).

13.4.14 EFFECT OF A RESET

A Reset disables the MSSP module and terminates the current transfer.

FIGURE 13-19: CLOCK ARBITRATION TIMING IN MASTER TRANSMIT MODE



13.4.16.3 Bus Collision During a Stop Condition

Bus collision occurs during a Stop condition if:

a) After the SDA pin has been de-asserted and allowed to float high, SDA is sampled low after the BRG has timed out.

b) After the SCL pin is de-asserted, SCL is sampled low before SDA goes high.

The Stop condition begins with SDA asserted low. When SDA is sampled low, the SCL pin is allowed to float. When the pin is sampled high (clock arbitration), the Baud Rate Generator is loaded with SSPADD<6:0> and counts down to 0. After the BRG times out, SDA is sampled. If SDA is sampled low, a bus collision has occurred. This is due to another master attempting to drive a data '0' (Figure 13-26). If the SCL pin is sampled low before SDA is allowed to float high, a bus collision occurs. This is another case of another master attempting to drive a data '0' (Figure 13-27).

FIGURE 13-26: BUS COLLISION DURING A STOP CONDITION (CASE 1)

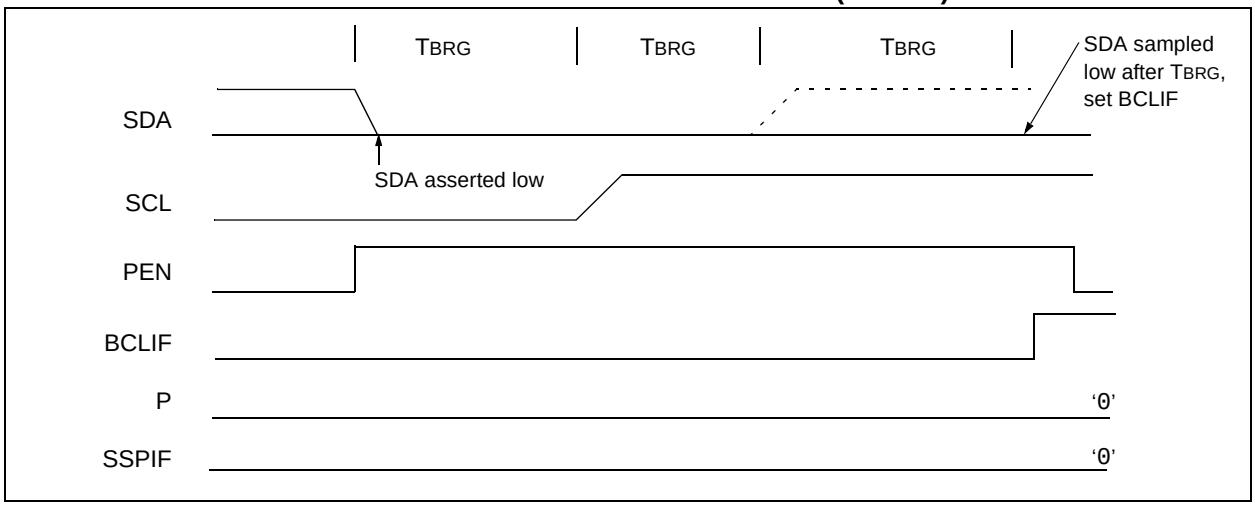
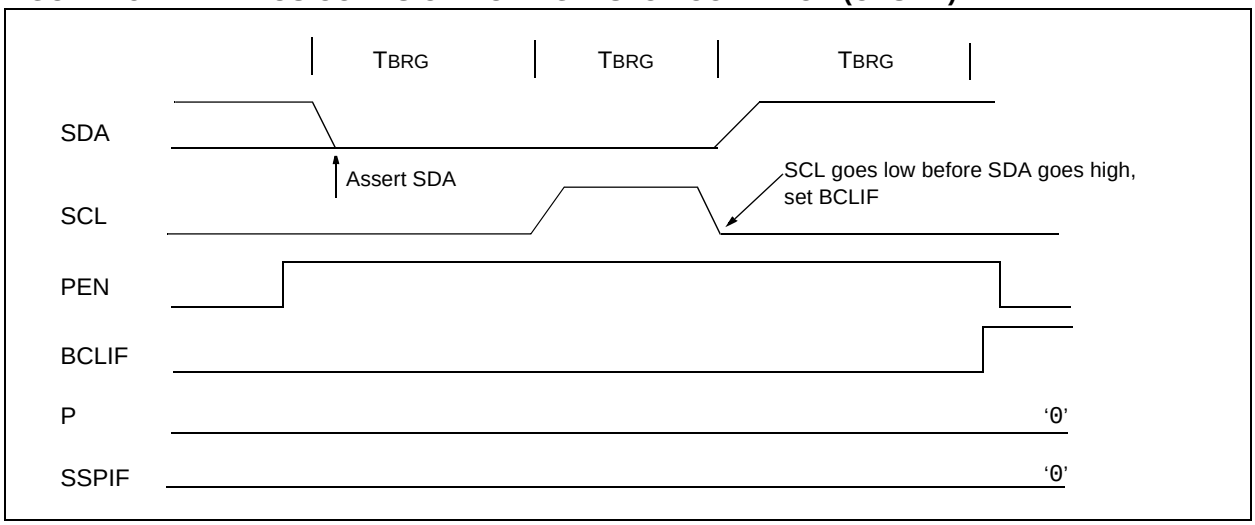


FIGURE 13-27: BUS COLLISION DURING A STOP CONDITION (CASE 2)



14.2.5 TIME-OUT SEQUENCE

On power-up, the time-out sequence is as follows: first, PWRT time-out is invoked after POR has expired, then OST is activated after the PWRT time-out has expired. The total time-out will vary based on oscillator configuration and $\overline{\text{PWRTE}}$ bit status. For example, in EC mode with $\overline{\text{PWRTE}}$ bit erased (PWRT disabled), there will be no time-out at all. Figures 14-4, 14-5 and 14-6 depict time-out sequences. The device can execute code from the INTOSC while OST is active by enabling Two-Speed Start-up or Fail-Safe Monitor (see **Section 4.7.2 "Two-Speed Start-up Sequence"** and **Section 4.8 "Fail-Safe Clock Monitor"**).

Since the time-outs occur from the POR pulse, if $\overline{\text{MCLR}}$ is kept low long enough, the time-outs will expire. Then, bringing $\overline{\text{MCLR}}$ high will begin execution immediately (see Figure 14-5). This is useful for testing purposes or to synchronize more than one PIC16F882/883/884/886/887 device operating in parallel.

Table 14-5 shows the Reset conditions for some special registers, while Table 14-4 shows the Reset conditions for all the registers.

14.2.6 POWER CONTROL (PCON) REGISTER

The Power Control register PCON (address 8Eh) has two Status bits to indicate what type of Reset that last occurred.

Bit 0 is $\overline{\text{BOR}}$ (Brown-out Reset). $\overline{\text{BOR}}$ is unknown on Power-on Reset. It must then be set by the user and checked on subsequent Resets to see if $\overline{\text{BOR}}$ = 0, indicating that a brown-out has occurred. The $\overline{\text{BOR}}$ Status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (BOREN<1:0> = 00 in the Configuration Word Register 1).

Bit 1 is $\overline{\text{POR}}$ (Power-on Reset). It is a '0' on Power-on Reset and unaffected otherwise. The user must write a '1' to this bit following a Power-on Reset. On a subsequent Reset, if $\overline{\text{POR}}$ is '0', it will indicate that a Power-on Reset has occurred (i.e., V_{DD} may have gone too low).

For more information, see **Section 3.2.2 "Ultra Low-Power Wake-up"** and **Section 14.2.4 "Brown-out Reset (BOR)"**.

TABLE 14-1: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Brown-out Reset		Wake-up from Sleep
	$\overline{\text{PWRTE}}$ = 0	$\overline{\text{PWRTE}}$ = 1	$\overline{\text{PWRTE}}$ = 0	$\overline{\text{PWRTE}}$ = 1	
XT, HS, LP	T_{PWRT} + 1024 • T_{OSC}	1024 • T_{OSC}	T_{PWRT} + 1024 • T_{OSC}	1024 • T_{OSC}	1024 • T_{OSC}
LP, T1OSCIN = 1	T_{PWRT}	—	T_{PWRT}	—	—
RC, EC, INTOSC	T_{PWRT}	—	T_{PWRT}	—	—

TABLE 14-2: STATUS/PCON BITS AND THEIR SIGNIFICANCE

POR	BOR	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Condition
0	x	1	1	Power-on Reset
u	0	1	1	Brown-out Reset
u	u	0	u	WDT Reset
u	u	0	0	WDT Wake-up
u	u	u	u	$\overline{\text{MCLR}}$ Reset during normal operation
u	u	1	0	$\overline{\text{MCLR}}$ Reset during Sleep

Legend: u = unchanged, x = unknown

TABLE 14-3: SUMMARY OF REGISTERS ASSOCIATED WITH BROWN-OUT

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
PCON	—	—	ULPWUE	SBOREN	—	—	$\overline{\text{POR}}$	$\overline{\text{BOR}}$	37
STATUS	IRP	RP1	RPO	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C	30

Legend: u = unchanged, x = unknown, – = unimplemented bit, reads as '0', q = value depends on condition. Shaded cells are not used by BOR.

Note 1: Other (non Power-up) Resets include $\overline{\text{MCLR}}$ Reset and Watchdog Timer Reset during normal operation.

14.5 Watchdog Timer (WDT)

The WDT has the following features:

- Operates from the LFINTOSC (31 kHz)
- Contains a 16-bit prescaler
- Shares an 8-bit prescaler with Timer0
- Time-out period is from 1 ms to 268 seconds
- Configuration bit and software controlled

WDT is cleared under certain conditions described in Table 14-7.

14.5.1 WDT OSCILLATOR

The WDT derives its time base from the 31 kHz LFINTOSC. The LTS bit of the OSCCON register does not reflect that the LFINTOSC is enabled.

The value of WDTCON is '---0 1000' on all Resets. This gives a nominal time base of 17 ms.

Note:	When the Oscillator Start-up Timer (OST) is invoked, the WDT is held in Reset, because the WDT Ripple Counter is used by the OST to perform the oscillator delay count. When the OST count has expired, the WDT will begin counting (if enabled).

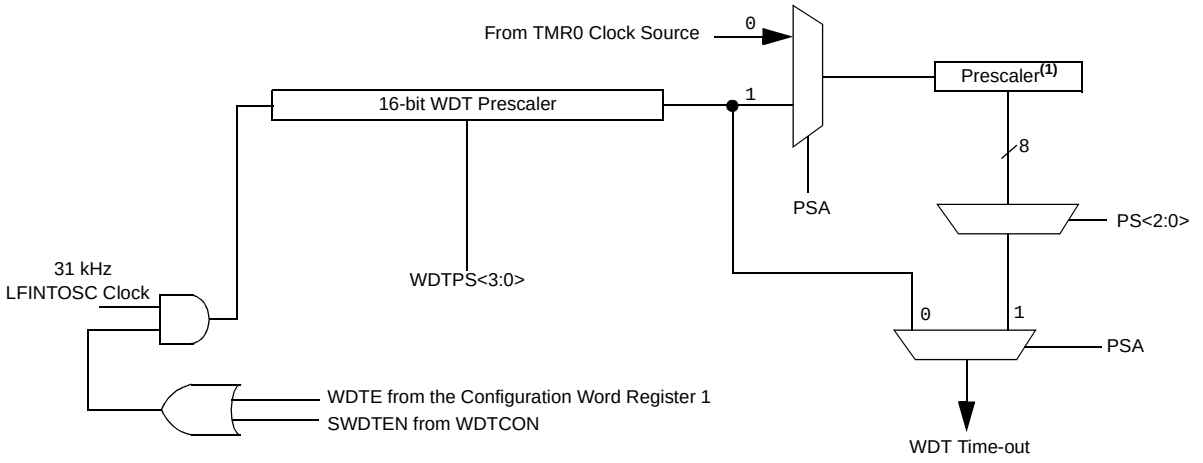
14.5.2 WDT CONTROL

The WDTE bit is located in the Configuration Word Register 1. When set, the WDT runs continuously.

When the WDTE bit in the Configuration Word Register 1 is set, the SWDTEN bit of the WDTCON register has no effect. If WDTE is clear, then the SWDTEN bit can be used to enable and disable the WDT. Setting the bit will enable it and clearing the bit will disable it.

The PSA and PS<2:0> bits of the OPTION register have the same function as in previous versions of the PIC16F882/883/884/886/887 family of microcontrollers. See **Section 5.0 "Timer0 Module"** for more information.

FIGURE 14-9: WATCHDOG TIMER BLOCK DIAGRAM



Note 1: This is the shared Timer0/WDT prescaler. See **Section 5.1.3 "Software Programmable Prescaler"** for more information.

TABLE 14-7: WDT STATUS

Conditions	WDT
WDTE = 0	Cleared
CLRWDT Command	
Oscillator Fail Detected	
Exit Sleep + System Clock = T1OSC, EXTRC, INTOSC, EXTCLK	
Exit Sleep + System Clock = XT, HS, LP	Cleared until the end of OST

16.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16, and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

16.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

16.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

16.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

TABLE 17-7: COMPARATOR SPECIFICATIONS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C								
Param No.	**Sym.**	**Characteristics**		**Min.**	**Typ†**	**Max.**	**Units**	**Comments**
CM01	VOS	Input Offset Voltage		—	± 5.0	± 10	mV	(VDD - 1.5)/2
CM02	VCM	Input Common Mode Voltage		0	—	VDD - 1.5	V	
CM03*	CMRR	Common Mode Rejection Ratio		+55	—	—	dB	
CM04*	TRT	Response Time	Falling	—	150	600	ns	**(Note 1)**
			Rising	—	200	1000	ns	
CM05*	TMC2COV	Comparator Mode Change to Output Valid		—	—	10	µs	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Response time is measured with one comparator input at (VDD - 1.5)/2 - 100 mV to (VDD - 1.5)/2 + 20 mV.

TABLE 17-8: COMPARATOR VOLTAGE REFERENCE (CVREF) SPECIFICATIONS

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym.**	**Characteristics**	**Min.**	**Typ†**	**Max.**	**Units**	**Comments**
CV01*	CLSB	Step Size(2)	— —	VDD/24 VDD/32	— —	V V	Low Range (VRR = 1) High Range (VRR = 0)
CV02*	CACC	Absolute Accuracy	— —	— —	± 1/2 ± 1/2	LSb LSb	Low Range (VRR = 1) High Range (VRR = 0)
CV03*	CR	Unit Resistor Value (R)	—	2k	—	Ω	
CV04*	CST	Settling Time(1)	—	—	10	µs	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Settling time measured while VRR = 1 and VR<3:0> transitions from '0000' to '1111'.

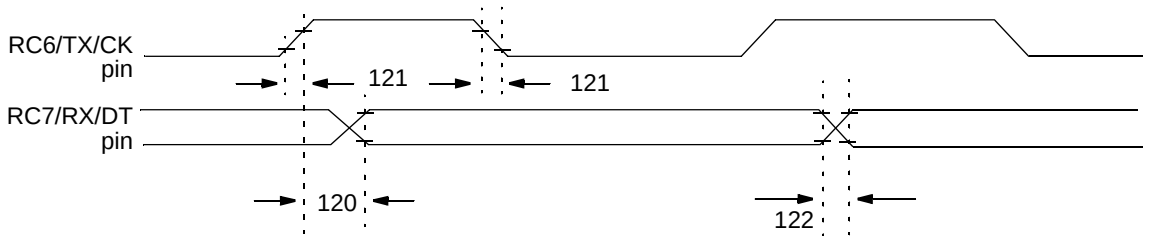
2: See **Section 8.10 "Comparator Voltage Reference"** for more information.

TABLE 17-9: VOLTAGE (VR) REFERENCE SPECIFICATIONS

VR Voltage Reference Specifications			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +125°C				
Param No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
VR01	VROUT	VR voltage output	0.5	0.6	0.7	V	
VR02*	TSTABLE	Settling Time	—	10	100*	µs	

* These parameters are characterized but not tested.

FIGURE 17-12: EUSART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

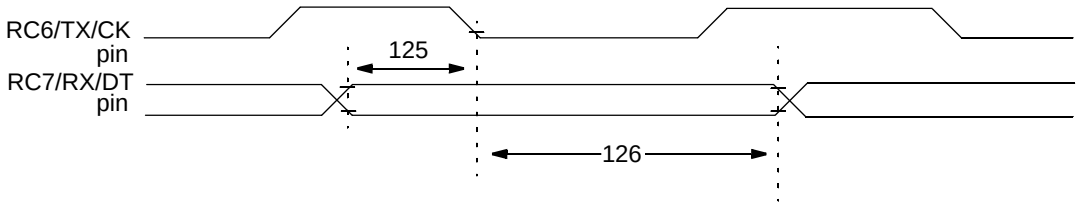


Note: Refer to Figure 17-3 for load conditions.

TABLE 17-12: EUSART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C						
Param. No.	**Symbol**	**Characteristic**	**Min.**	**Max.**	**Units**	**Conditions**
120	TCKH2DTV	SYNC XMIT (Master & Slave) Clock high to data-out valid	—	40	ns	
121	TCKRF	Clock out rise time and fall time (Master mode)	—	20	ns	
122	TDTRF	Data-out rise time and fall time	—	20	ns	

FIGURE 17-13: EUSART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



Note: Refer to Figure 17-3 for load conditions.

TABLE 17-13: EUSART SYNCHRONOUS RECEIVE REQUIREMENTS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C						
Param. No.	**Symbol**	**Characteristic**	**Min.**	**Max.**	**Units**	**Conditions**
125	TDTV2CKL	SYNC RCV (Master & Slave) Data-hold before CK ↓ (DT hold time)	10	—	ns	
126	TCKL2DTL	Data-hold after CK ↓ (DT hold time)	15	—	ns	

17.9 High Temperature Operation

This section outlines the specifications for the following devices operating in the high temperature range between -40°C and 150°C.(4)

- PIC16F886
- PIC16F887

When the value of any parameter is identical for both the 125°C Extended and the 150°C High Temp. temperature ranges, then that value will be found in the standard specification tables shown earlier in this chapter, under the fields listed for the 125°C Extended temperature range. If the value of any parameter is unique to the 150°C High Temp. temperature range, then it will be listed here, in this section of the data sheet.

If a Silicon Errata exists for the product and it lists a modification to the 125°C Extended temperature range value, one that is also shared at the 150°C high temp. temperature range, then that modified value will apply to both temperature ranges.

Note 1: Writes are **not allowed** for Flash program memory above 125°C.

2: The temperature range indicator in the catalog part number and device marking is “H” for -40°C to 150°C.

Example: PIC16F887T-H/PT indicates the device is shipped in a Tape and reel configuration, in the TQFP package, and is rated for operation from -40°C to 150°C.

3: The +150°C version of the PIC16F886 and PIC16F887 will not be offered in PDIP. It will only be offered in SSOP, SOIC, QFN and TQFP.

4: AEC-Q100 reliability testing for devices intended to operate at 150°C is 1,000 hours. Any design in which the total operating time from 125°C to 150°C will be greater than 1,000 hours is not warranted without prior written approval from Microchip Technology Inc.

TABLE 17-17: ABSOLUTE MAXIMUM RATINGS

Parameter	Source/Sink	Value	Units
Max. Current: V_{DD}	Source	20	mA
Max. Current: V_{SS}	Sink	50	mA
Max. Current: Pin	Source	5	mA
Max. Current: Pin	Sink	10	mA
Max. Pin Current: at V_{OH}	Source	3	mA
Max. Pin Current: at V_{OL}	Sink	8.5	mA
Max. Port Current: A, B, and C combined	Source	20	mA
Max. Port Current: A, B, and C combined	Sink	50	mA
Max. Junction Temperature		155	°C

Note: Stresses above those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure above maximum rating conditions for extended periods may affect device reliability.

FIGURE 18-27: VOL vs. IOL OVER TEMPERATURE (VDD = 5.0V)

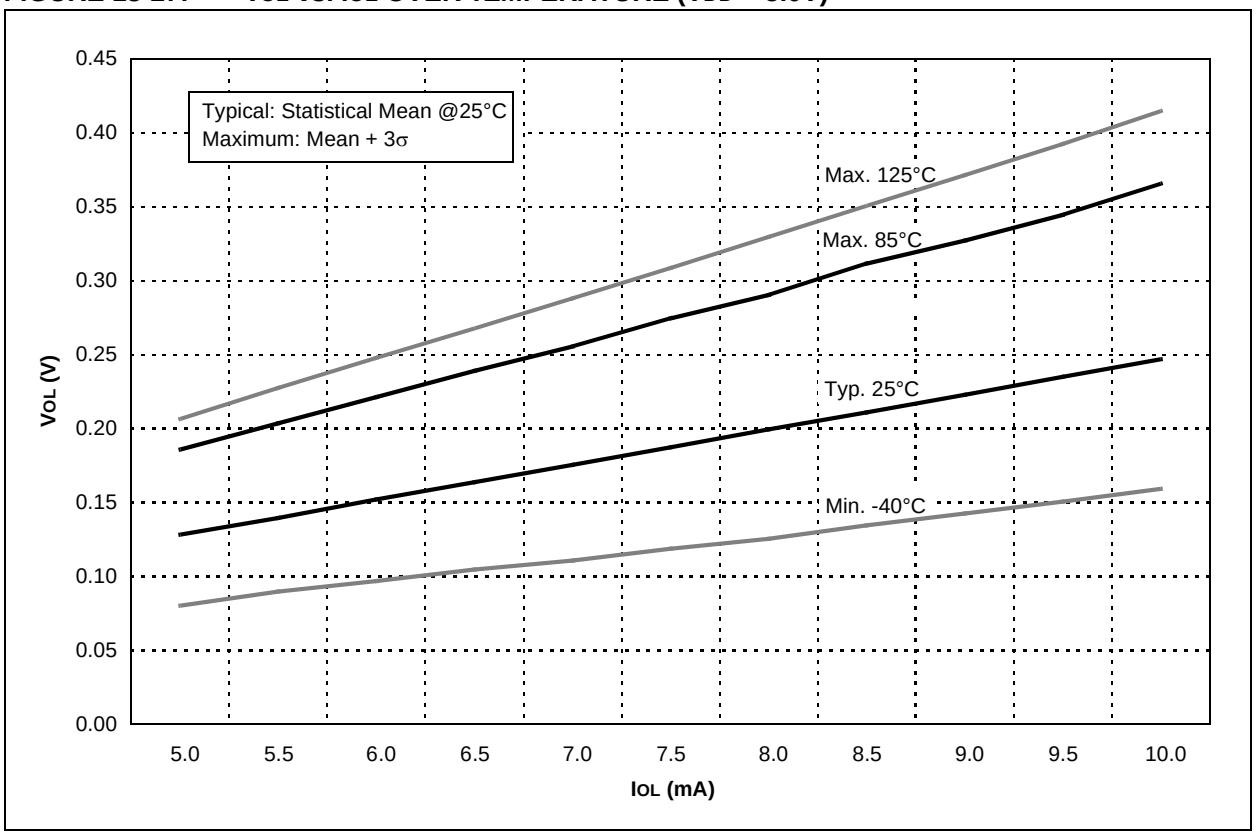


FIGURE 18-28: VOH vs. IOH OVER TEMPERATURE (VDD = 3.0V)

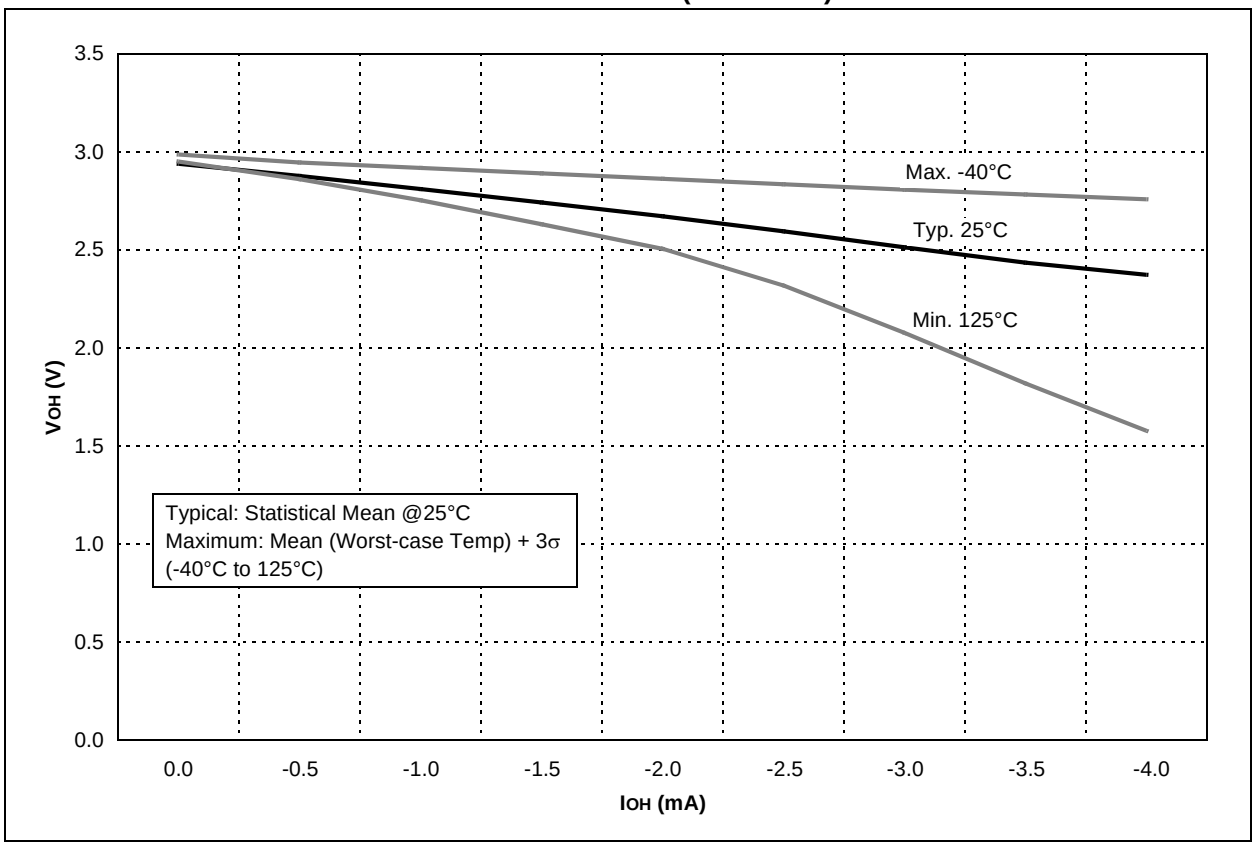


FIGURE 18-43: TYPICAL VP6 REFERENCE VOLTAGE vs. VDD (25°C)

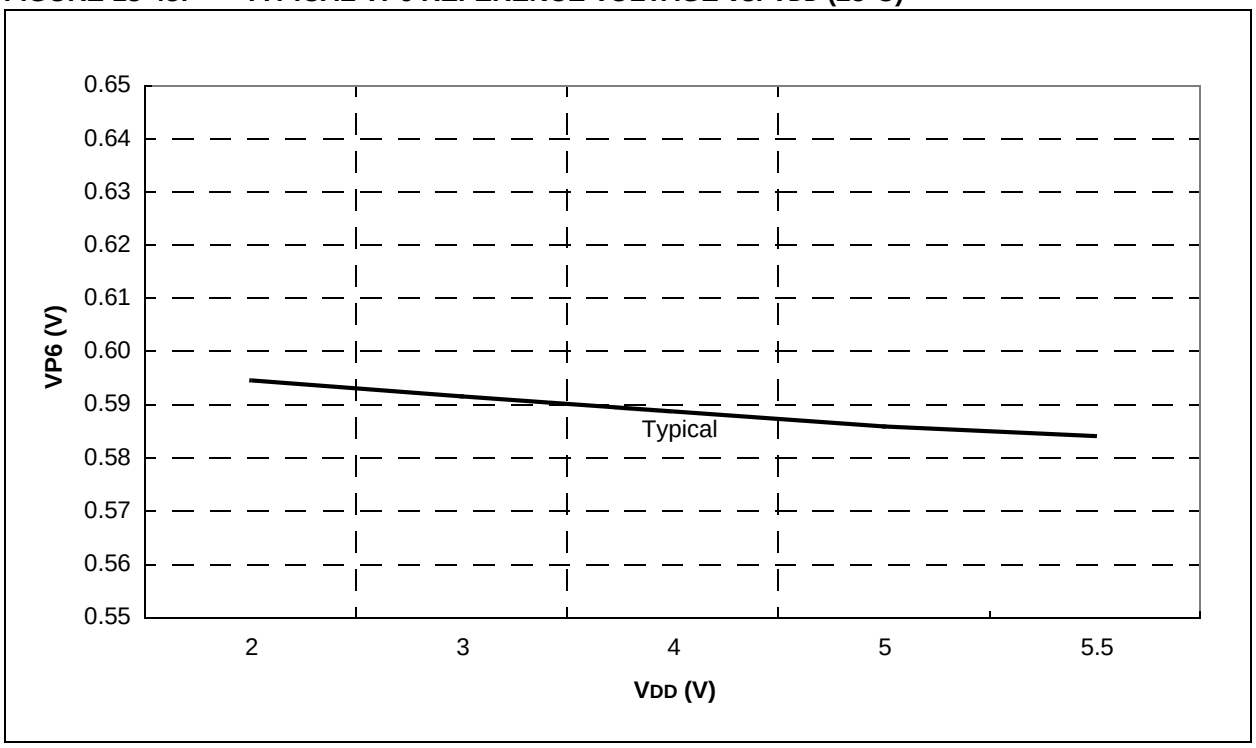
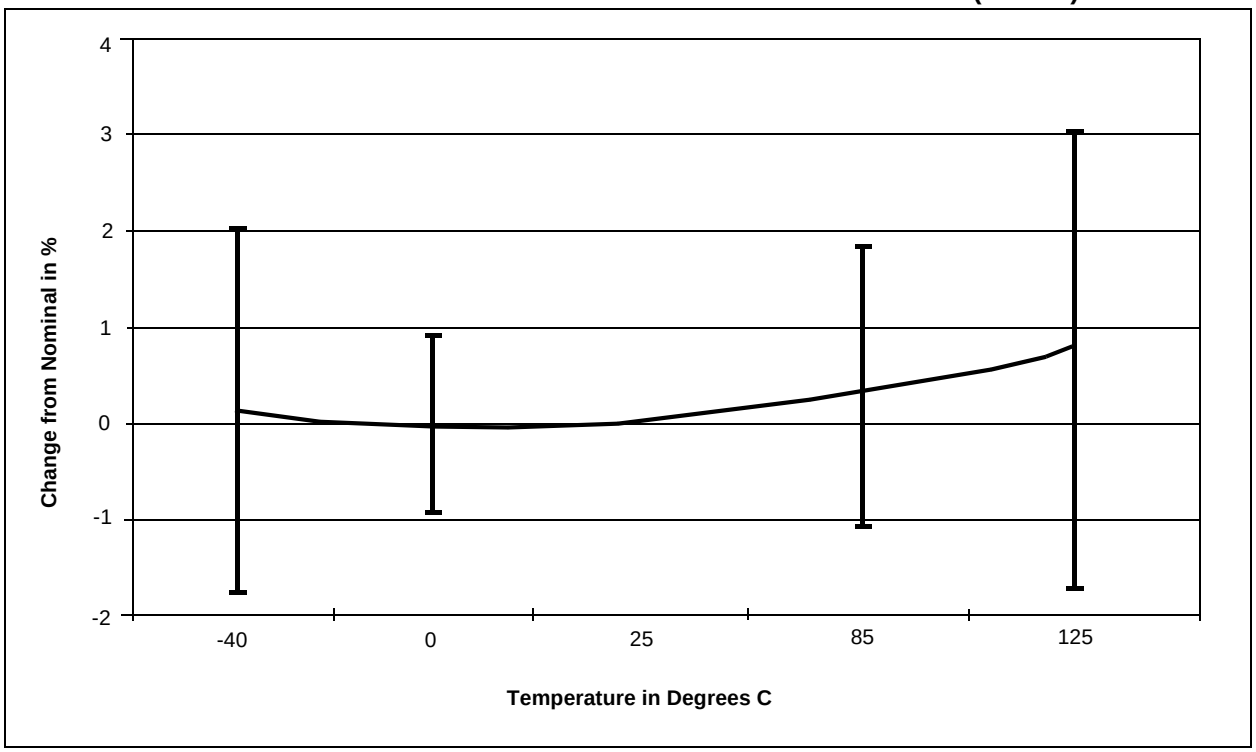
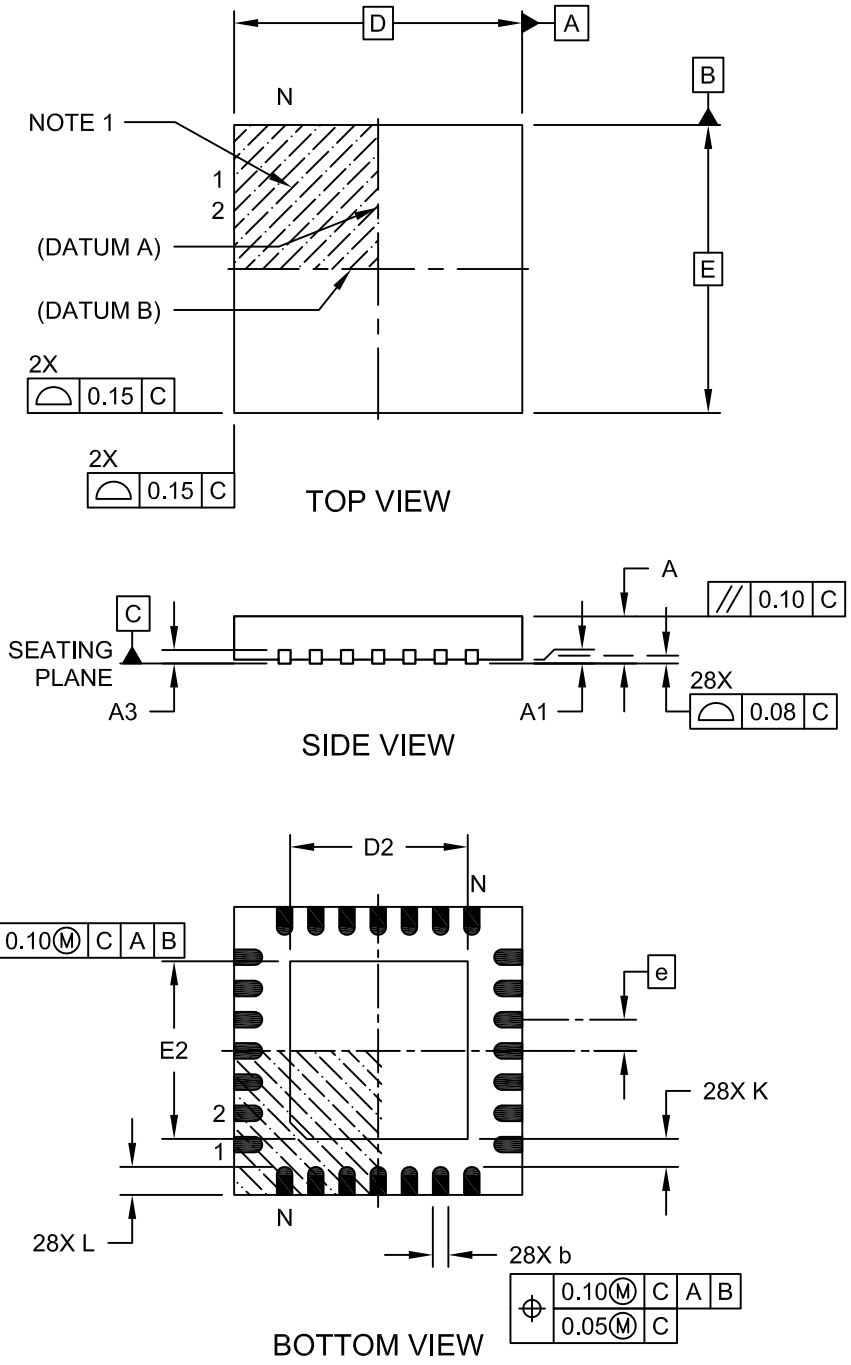


FIGURE 18-44: VP6 DRIFT OVER TEMPERATURE NORMALIZED AT 25°C (VDD 5V)



28-Lead Plastic Quad Flat, No Lead Package (ML) - 6x6 mm Body [QFN]
With 0.55 mm Terminal Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-105C Sheet 1 of 2